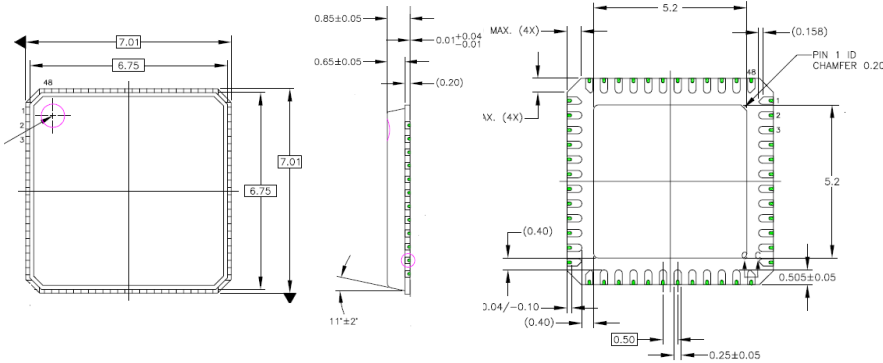


Package Thermal Datasheet

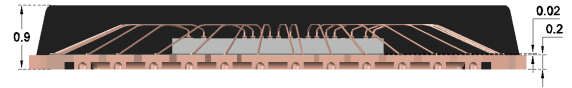
PG-VQFN-48-31



1. Package Dimensions



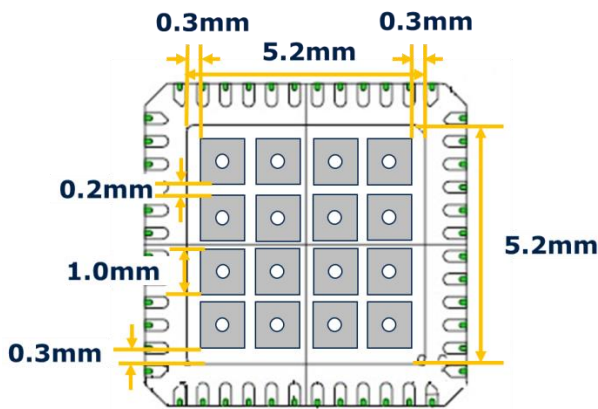
Package outline



Side view and 3D view (TLE986x)

2. PCB and Thermal Vias

Only JEDEC board is used for thermal assessment.



16 JEDEC thermal vias

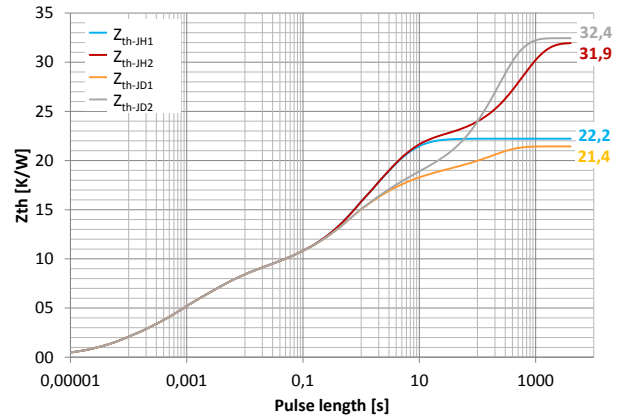
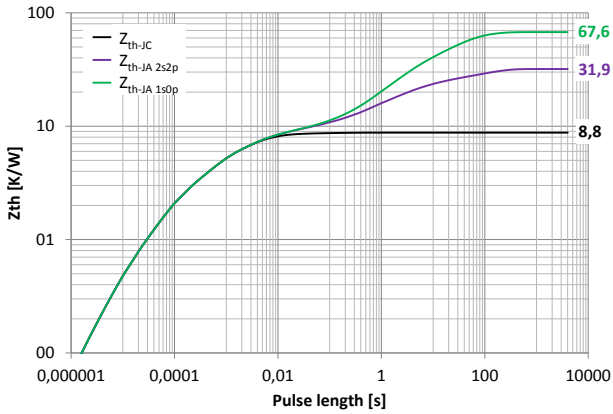
3. Products in PG-VQFN-48-31

Sales Description	TLE986x
Product Group	Proteus
Interconnects	CU-5N 25µM
FE Technology	SPT9_65V_8
Chip Area & Thickness	3.158*2.978=9,405mm ² & 220µm
DMOS %	6%
Die Attach Material & Thickness	CRM 1079 S & 20µm
Leadframe Material & Thickness	C 19400 & 200µm
Mould Compound	EME G700 CD
Package Thickness	0.85mm

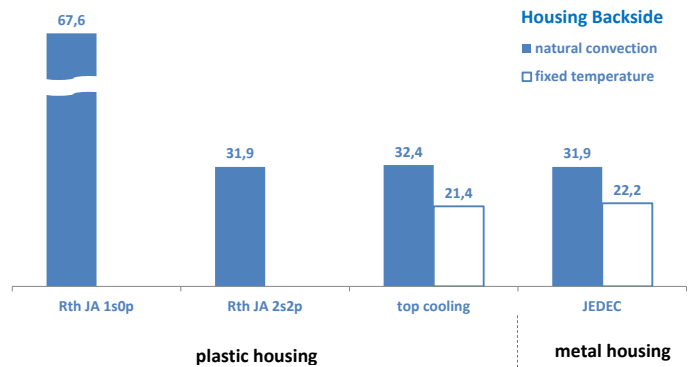
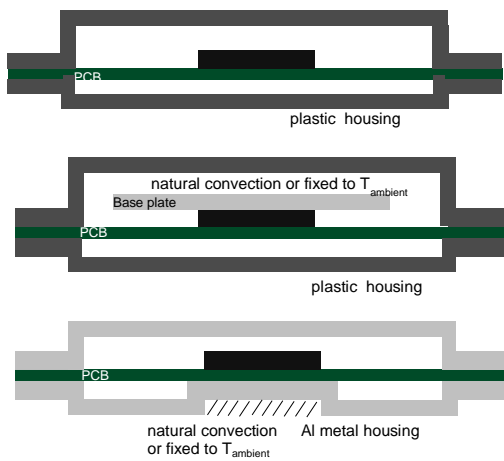


4. TLE986x

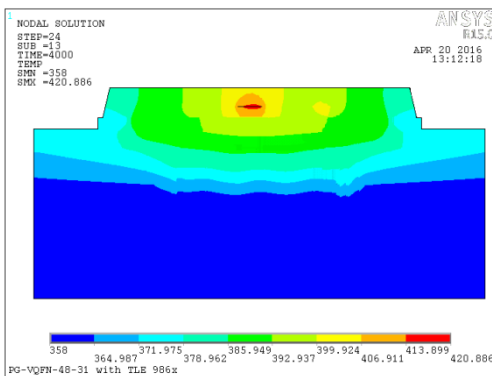
4.1 Thermal Impedance



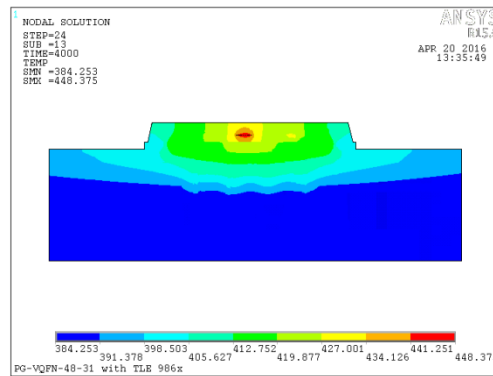
4.2 Influence of PCB Board



4.3 Temperature Distributions



JEDEC fixed temperature



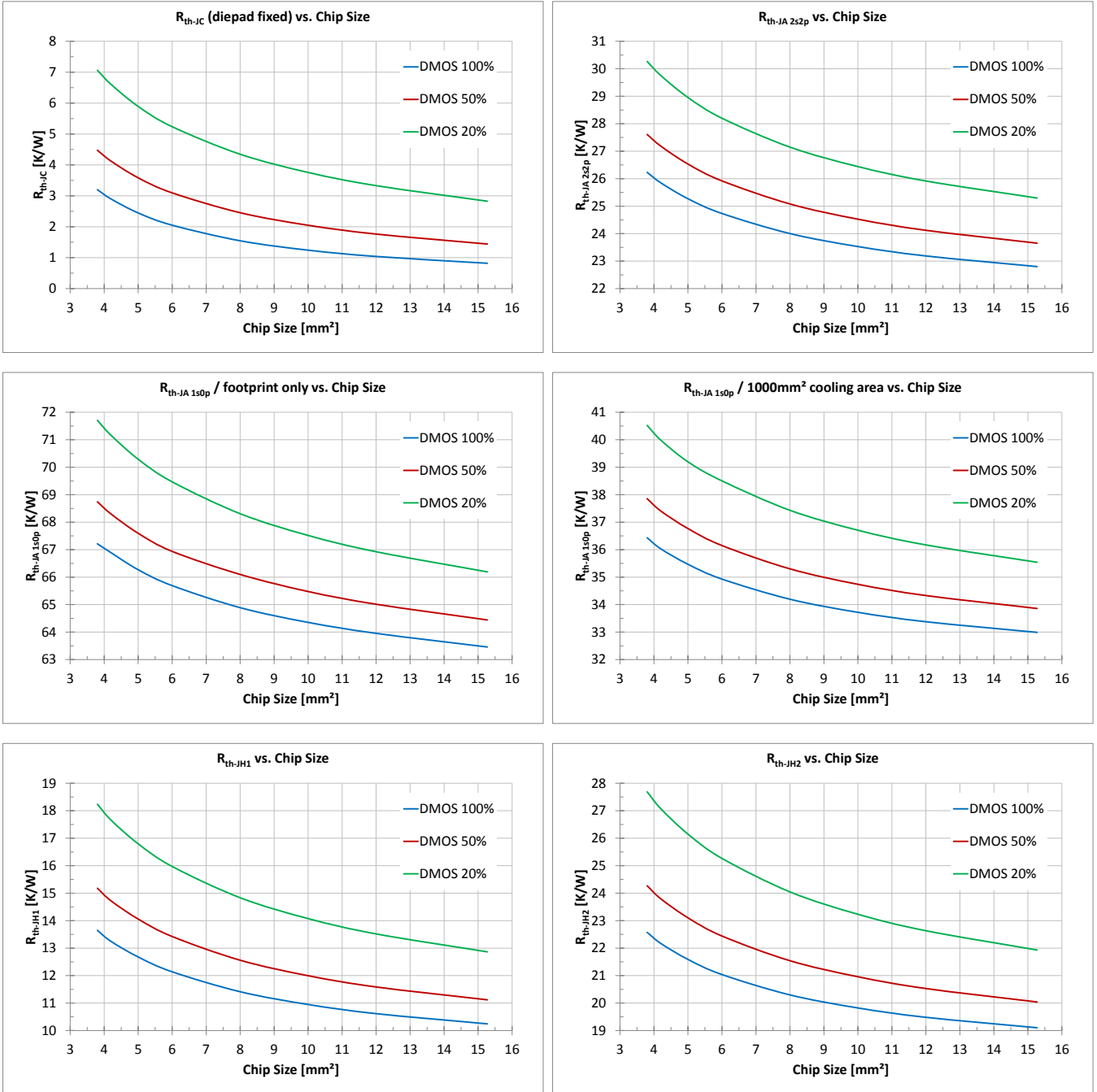
JEDEC natural convection

Package Thermal Datasheet

PG-VQFN-48-31

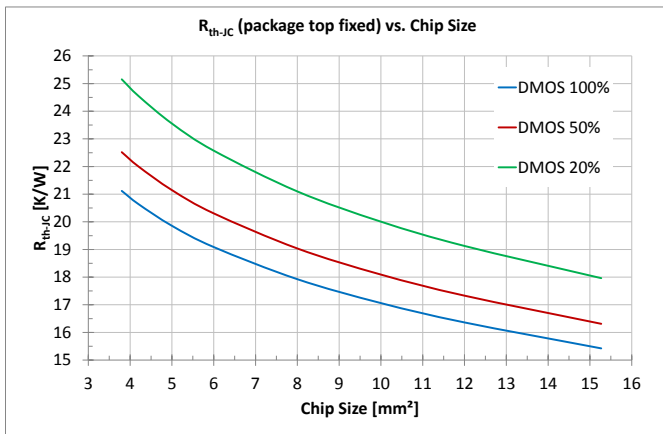
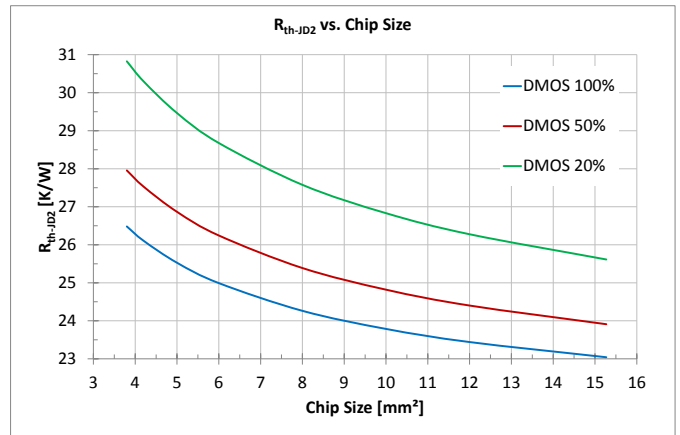
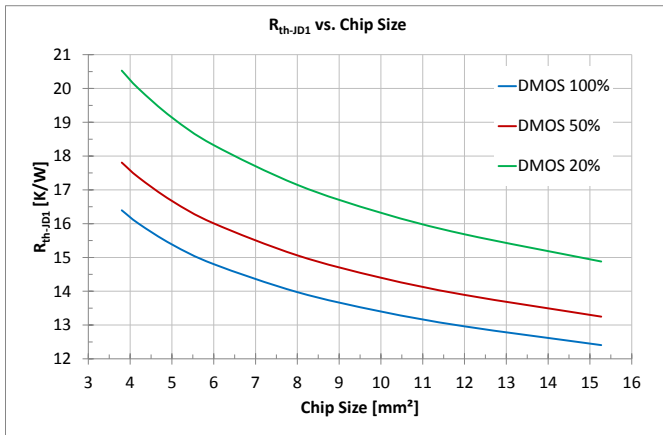


5. PG-VQFN-48-31 Platform ($T_{\text{ambient}}=85^{\circ}\text{C}$, JEDEC Board)



Package Thermal Datasheet

PG-VQFN-48-31



6. Thermal Reports List

Report Description	Report Number
TLEg86x	ThP-VQFN-02
PG-VQFN platform	ThP-VQFN-01